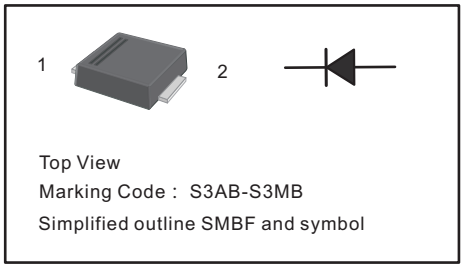
Surface Mount General Purpose Silicon Rectifiers

Reverse Voltage - 50 to 1000 V

Forward Current - 3 A

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Top View
Marking Code : S3AB-S3MB
Simplified outline SMBF and symbol

FEATURES
- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA
- Case: SMBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 57mg / 0.002oz

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.
Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	S3ABF	S3BBF	S3DBF	S3GBF	S3JBF	S3KBF	S3MBF	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at T_c = 115 °C	$I_{F(AV)}$	3							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	100							A
Maximum Instantaneous Forward Voltage at 3 A	V_F	1.1							V
Maximum DC Reverse Current T_a = 25 °C at Rated DC Blocking Voltage T_a =125 °C	I_R	5 150							μA
Typical Junction Capacitance (1)	C_j	35							pF
Typical Thermal Resistance (2)	$R_{\theta JA}$ $R_{\theta JC}$	45 15							°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							°C

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C
(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Copyright@ SEMIPOWER Electronic Technology Co., Ltd. All rights reserved. 2016 Rev 1.0

Fig.1 Forward Current Derating Curve

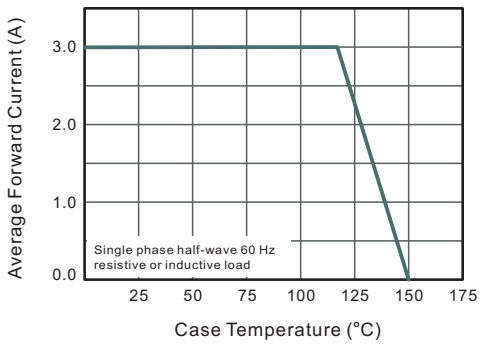


Fig.2 Typical Reverse Characteristics

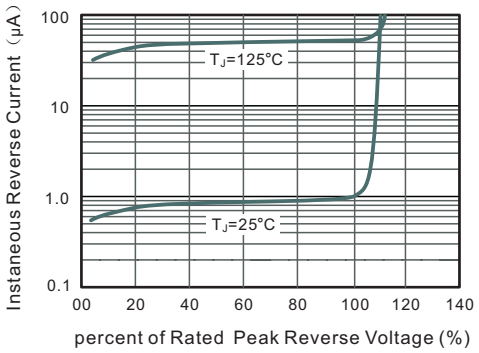


Fig.3 Typical Forward Characteristic

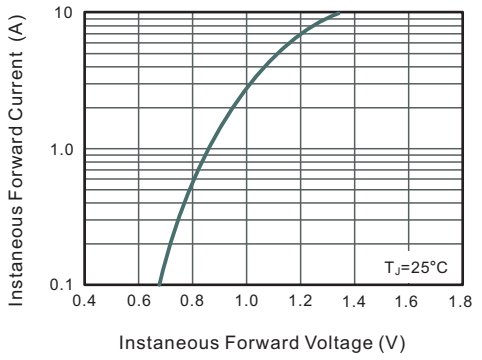


Fig.4 Typical Junction Capacitance

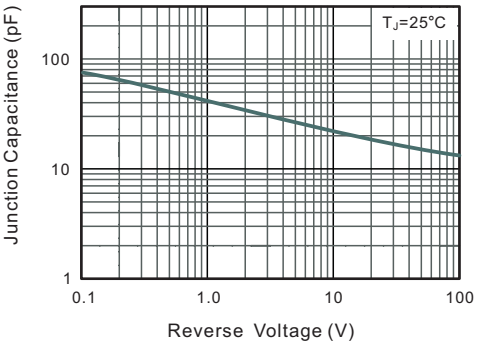
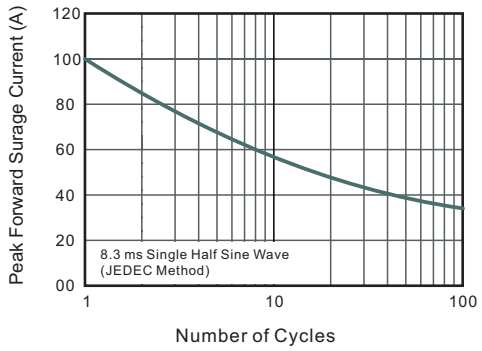


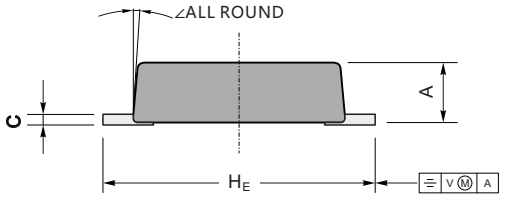
Fig.6 Maximum Non-Repetitive Peak Forward Surage Current

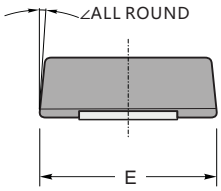


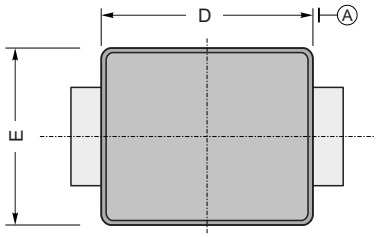
Copyright@ SEMIPOWER Electronic Technology Co., Ltd. All rights reserved.

PACKAGE OUTLINE

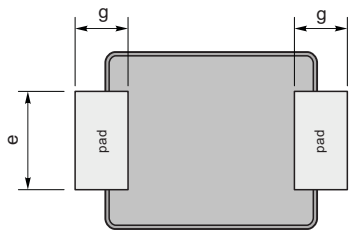
Plastic surface mounted package; 2 leads SMBF







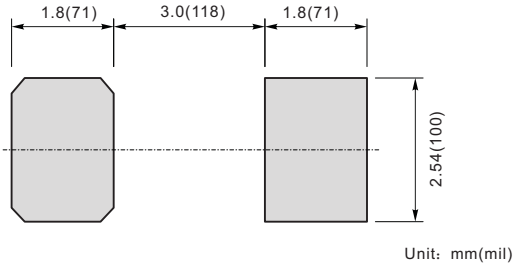
Top View



Bottom View

UNIT		A	C	D	E	H_E	e	g	∠
mm	max	1.3	0.26	4.4	3.7	5.5	2.2	1.0	9°
	min	1.1	0.18	4.2	3.5	5.1	1.9		
mil	max	51	10	173	146	216	86	40	
	min	43	7	165	138	200	75		

The recommended mounting pad size



Marking

Type number	Marking code
S3ABF	S3AB
S3BBF	S3BB
S3DBF	S3DB
S3GBF	S3GB
S3JBF	S3JB
S3KBF	S3KB
S3MBF	S3MB

Copyright@ SEMIPOWER Electronic Technology Co., Ltd. All rights reserved. 2016 Rev 1.0